TAIWAN SEMICONDUCTOR

Product/ Process Change Notification

1. PCN No.:	*QPCN13004*
2. Subject:	*Shottky FE(Front End) wafer production and technology change*
3. To:	*All customers involved*
4. Issued by:	*HQ(Headquarter) QRA Owen Wang*
5. Issue date:	*8-Mar-2013*
6. Proposed first ship date for change:	*10-Jun-2013*

7. Affected Product Identification

See attached detailed Part-No. list.

8. Change Description : (OLD Vs. NEW Comparison)

Old:	New:
➢ I-Lan TSC own wafer fab located in Taiwan. ➢ Technology (see att. comparison report)	➢ 1st subcon wafer fab located in China. ➢ 2nd subcon wafer fab located in China. ➢ Technology (See att. comparison report)

9. Reason for Change:

Risk management & Capacity enlargement.(2 new Chinese subcon instead of one Taiwan TSC source)

10. Anticipated Impact: (form, fit, function, quality or reliability)

1. Product outline:	*No change*
2. Inner construction changed:	*Die source and technology change*
3. Electrical specifications:	*No significant different attach refer to comparison report*
4. Reliability performance:	*Per AQC-Q101 all test accepted*
5. Data sheet:	*No change*
6. Packing code (order code):	*No change*
7. Identification/Traceability:	*By date code*

11. Qualification plan/result:

Refer to	
PPAP	*Available on demand*
Comparison report	*See attached*

12. Sample availability Date:	*8-Mar-2013*
13. Tentative implementation date:	*8-Mar-2013*

14. Remarks

15. Customer feedback required latest: **(should we receive no feedback; the change will be deemed as accepted!)**	***15-Apr-2013***
16. Approved by:	*Quayer Chen*

(HQ4PE01-B)

Product/ Process Change Notification
Customer Approval Form_QPCN13004

(Please tick the field what is valid for you!)

| ☐ | **We agree with this proposed change and its schedule.** |

☐	**We have objections**

☐	**We need more information:**

☐	**We need sample:**

Company:	
Name:	
Address:	

Signature:		**Date:**	

(HQ4PE01-B)